



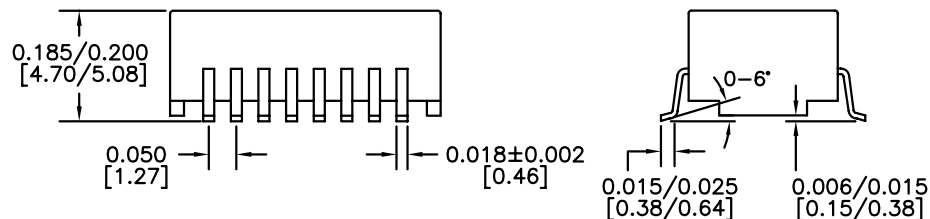
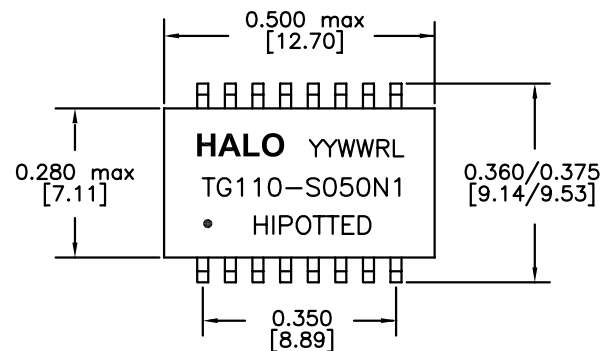
PART NO. : TG110-S050N1RL

16PIN SMT ISOLATION MODULE FOR 10/100BASE-TX
IEEE802.3u APPLICATIONS

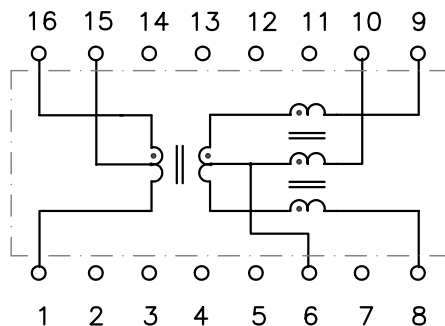
LEAD-FREE/RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

OPERATING TEMPERATURE 0/+70°C



DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



ELECTRICAL SPECIFICATIONS @25° C

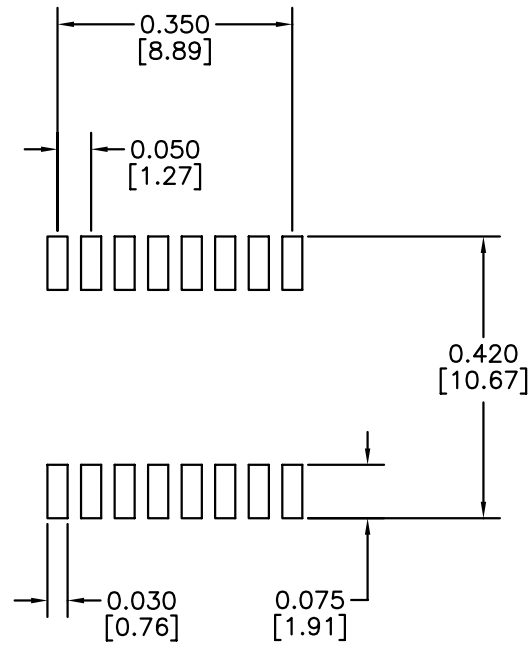
URNS RATIO	
P1-16:P8-9	1CT:1CT ±3%
OCL (100KHz,0.1Vrms,8mA)	
P1-16	350μH min
DCR P1-16	0.9Ω max
LL P1-16	0.4μH max
Cw/w	35pF max
INSERTION LOSS	
0.1-100MHz	-1.1dB max
RETURN LOSS	
0.5-30MHz	-18dB min
40MHz	-15.5dB min
50MHz	-13.6dB min
60-80MHz	-12dB min
CMR 0.1-100MHz	-35dB typ
ISOLATION	1,500Vrms

HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION TRANSFORMER	
FOR	FAST ETHERNET	
PART NO.	TG110-S050N1RL	
SCALE	NONE	PAGE 1 OF 2

SIGNATURES	DATE	REV.		
DRAWN PETER LU	2/16/06	A		
CHECKED				
APPROVED				
FILE S050N1RL.DWG				



RECOMMENDED SOLDER PAD DIMENSIONS
 DIIMENSIONS: Inch [mm]

HALO/PBL CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE	TITLE ISOLATION TRANSFORMER		SIGNATURES		DATE	REV.		
	FOR FAST ETHERNET		DRAWN PETER LU		2/16/06	A		
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	PAGE 2 OF 2	FILE S050N1RL.DWG						